MITSUI
KINZOKU

MW-G-VSP

- MW-G-VSP 铜箔低棱线特性具极佳的绝缘效果与具优越的蚀刻性之符合新一代环保要求之电解铜箔。
  MW-G-VSP foil with very low profile to have excellent insulation result and good etchability, and comply with environment regulation.
- 具较低的棱线为应用于高速讯号传输板最佳铜箔材料。
  Very low profile of MW-G-VSP makes it an excellent material to apply to high speed transmission board.

用途/Application

·高速讯号传输板
/HSD (High speed digital)

结构 /Composition

生产地点 /Production Site

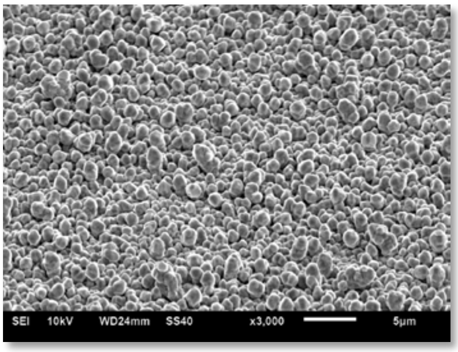
·台湾 / Taiwan

特性代表值/Representative data

	μ m	Rz (μ m)	Tensile Strength (N/mm2)	Elogation (%)	Peel Strength (kg/cm)
MW-G-VSP	18	2.5	350	8	1.0
	35	2.5	350	16	1.3
	70	2.5	350	19	1.5

※上述表列为代表性数据非保证值。
This is representative data, not guarantee.

处理面/Laminate side



阻剂面 / resist side